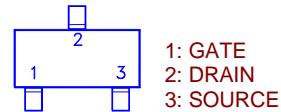
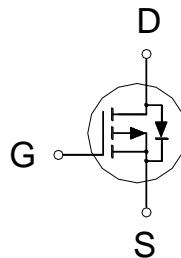


NIKO-SEM
**P-Channel Enhancement Mode
Field Effect Transistor**
PM523BA
SOT-23(S)
Halogen-Free & Lead-Free
PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D
-30V	80mΩ	-2.5A

**ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-2.5	A
		-2	
Pulsed Drain Current ¹	I_{DM}	-10	
Power Dissipation	P_D	0.8	W
		0.5	
Junction & Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$	139	70	°C / W
Junction-to-Case	$R_{\theta JC}$			

¹ Pulse width limited by maximum junction temperature.² The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	Typ	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.5	-3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24\text{V}, V_{GS} = 0\text{V}$			-1	μA
		$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}, T_J = 70^\circ\text{C}$			-10	
Drain-Source On-State Resistance ¹	$R_{DS(\text{on})}$	$V_{GS} = -10\text{V}, I_D = -2\text{A}$		67	80	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -1.5\text{A}$		95	120	

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Forward Transconductance ¹	g_{fs}	$V_{DS} = -10V, I_D = -2.5A$	6.2		S
DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -15V, f = 1MHz$	270		pF
Output Capacitance	C_{oss}		46		
Reverse Transfer Capacitance	C_{rss}		37		
Total Gate Charge ²	Q_g		7.2		
Gate-Source Charge ²	Q_{gs}	$V_{DS} = -15V, I_D = -2A, V_{GS} = -10V$	1.1		nC
Gate-Drain Charge ²	Q_{gd}		1.8		
Turn-On Delay Time ²	$t_{d(on)}$		15		
Rise Time ²	t_r		36		
Turn-Off Delay Time ²	$t_{d(off)}$	$I_D \approx -2A, V_{GS} = -10V, R_{GEN} = 6\Omega$	43.5		nS
Fall Time ²	t_f		35		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)					
Continuous Current	I_S			-0.7	A
Forward Voltage ¹	V_{SD}	$I_F = -2A, V_{GS} = 0V$		-1.1	V
Reverse Recovery Time	t_{rr}	$I_F = -2A, dI_F/dt = 100A / \mu s$	11		nS
Reverse Recovery Charge	Q_{rr}		3.3		nC

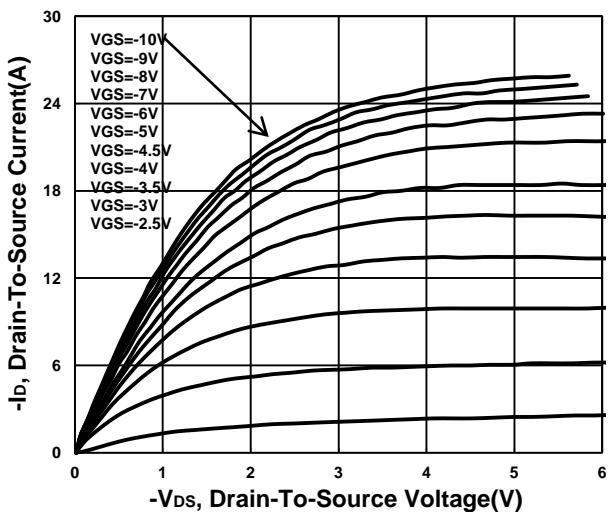
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

NIKO-SEM

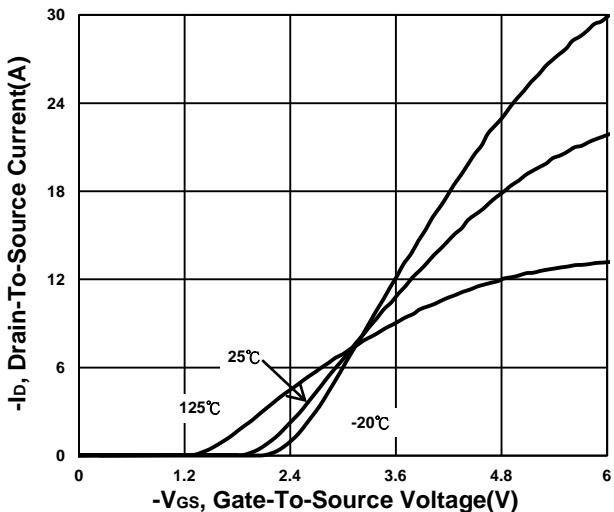
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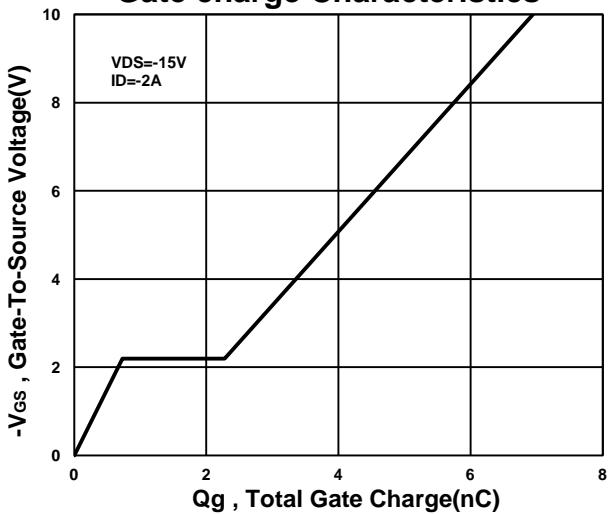
Output Characteristics



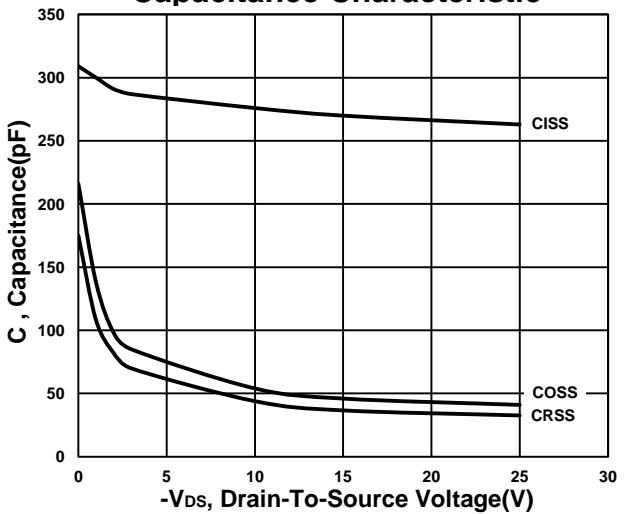
Transfer Characteristics



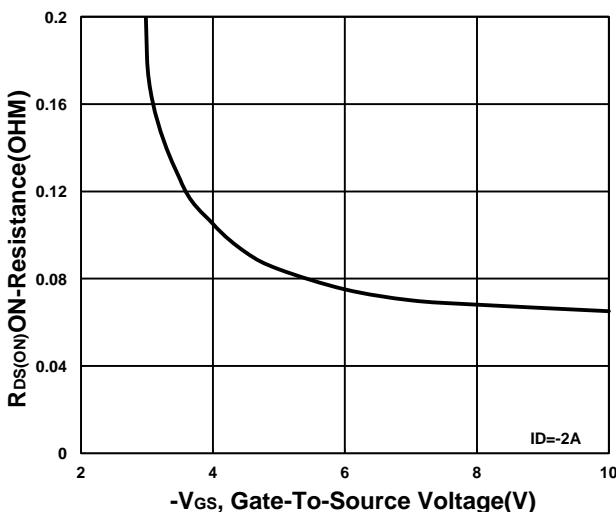
Gate charge Characteristics



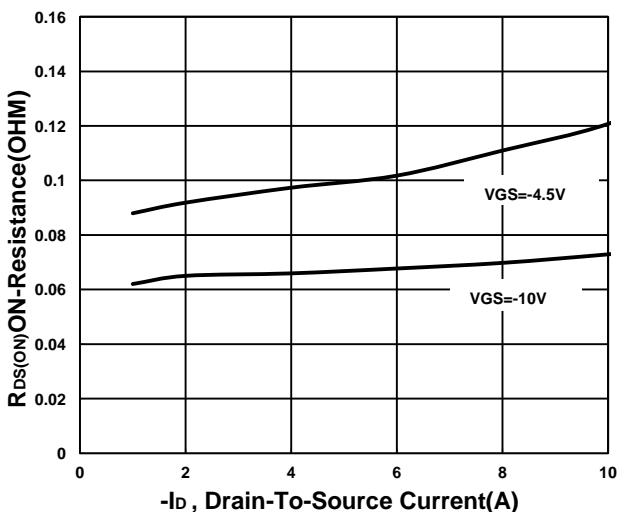
Capacitance Characteristic



On-Resistance VS Gate-To-Source



On-Resistance VS Drain Current

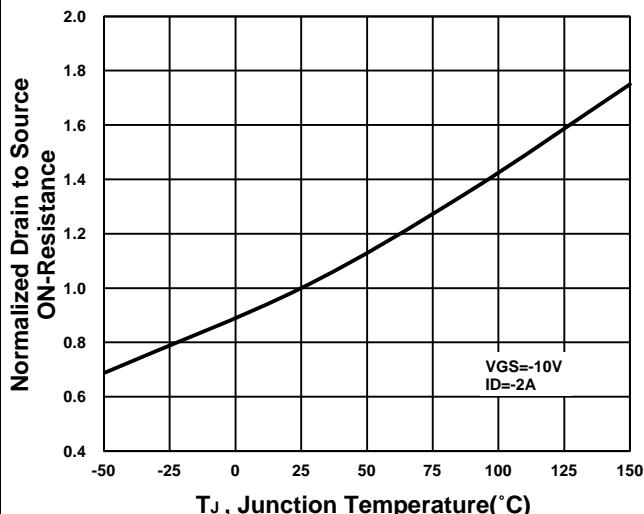


NIKO-SEM

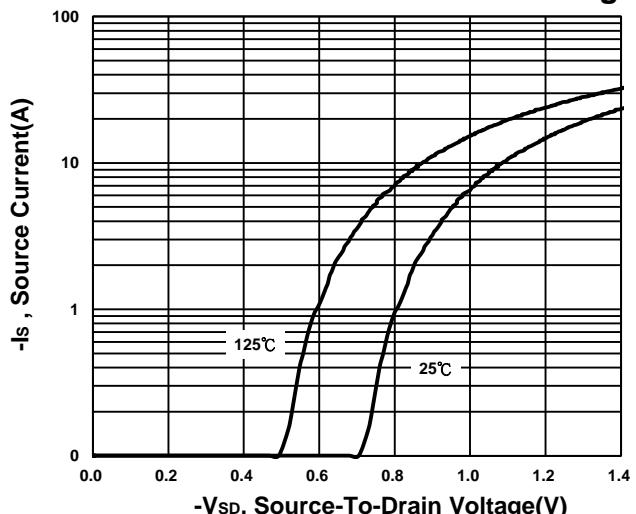
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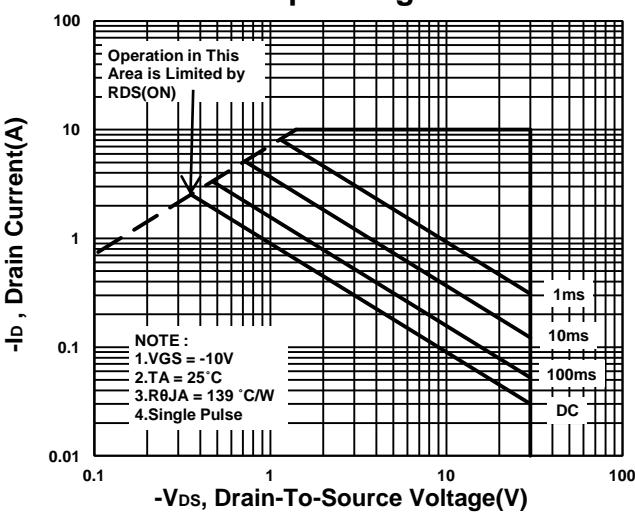
On-Resistance VS Temperature



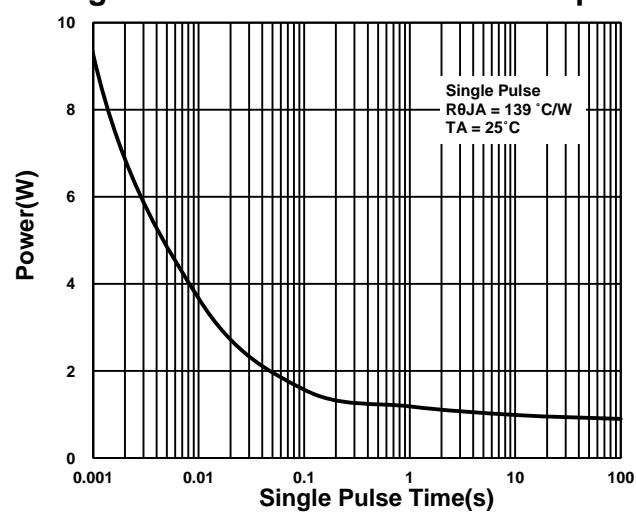
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

